

## Publikationen

(2020): Education 4.0: An Adaptive Framework with Artificial Intelligence, Raspberry Pi and Wearables- Innovation for Creating Value. In: Proceedings of the 2020 IEEE 26th International Symposium for Design and Technology in Electronic Packaging (SIITME). DOI: 10.1109/SIITME50350.2020.9292148.

(2020): Education 4.0 - Jump to Innovation IoT in Higher Education. In: Proceedings of the 2019 IEEE 25th International Symposium for Design and Technology in Electronic Packaging (SIITME) [Oct 23-26, 2019; Cluj-Napoca, Romania], New York, NY, USA. DOI: 10.1109/SIITME47687.2019.8990825.